

Interface and switching (30V, 200mA)

2SK2731

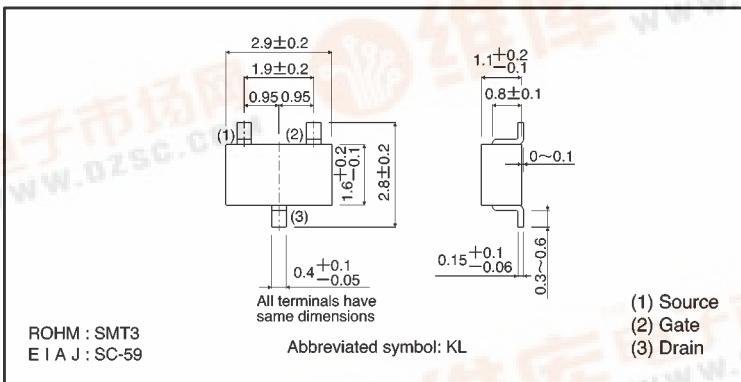
●Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Low-voltage drive (4V).
- 4) Easily designed drive circuits.
- 5) Easy to parallel.

●Structure

Silicon N-channel
MOSFET

●External dimensions (Units: mm)

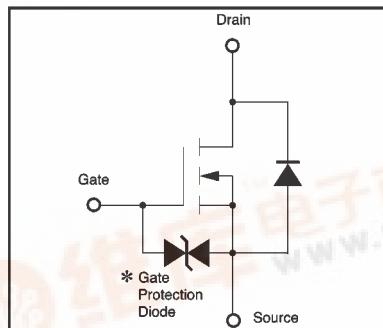


●Absolute maximum ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Limits	Unit
Drain-source voltage	V_{DSS}	30	V
Gate-source voltage	V_{GSS}	± 20	V
Drain current	Continuous	I_D	mA
	Pulsed	I_{DP}^*	mA
Reverse drain current	Continuous	I_{DR}	mA
	Pulsed	I_{DRP}^*	mA
Total power dissipation	P_D	200	mW
Channel temperature	T_{ch}	150	°C
Storage temperature	T_{stg}	-55~+150	°C

* $P_w \leq 10 \mu\text{s}$, Duty cycle $\leq 1\%$

●Equivalent circuit



* A protection diode is included between the gate and the source terminals to protect the diode against static electricity when the product is in use. Use a protection circuit when the fixed voltage are exceeded.

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Gate-source leakage	I_{GSS}	—	—	± 10	μA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
Drain-source breakdown voltage	$V_{(BR) DSS}$	30	—	—	V	$I_D = 1\text{mA}, V_{GS} = 0\text{V}$
Zero gate voltage drain current	I_{DSS}	—	—	10	μA	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}$
Gate threshold voltage	$V_{GS(\text{th})}$	1.0	—	2.5	V	$V_{DS} = 10\text{V}, I_D = 1\text{mA}$
Static drain-source on-state resistance	$R_{DS(on)}$	—	1.5 2.8	2.8 4.5	Ω	$I_D = 0.1\text{A}, V_{GS} = 10\text{V}$ $I_D = 0.1\text{A}, V_{GS} = 4\text{V}$
Forward transfer admittance	$ Y_{fs} ^*$	100	—	—	mS	$I_D = 0.1\text{A}, V_{DS} = 10\text{V}$
Input capacitance	C_{iss}	—	25	—	pF	$V_{DS} = 10\text{V}$
Output capacitance	C_{oss}	—	15	—	pF	$V_{GS} = 0\text{V}$
Reverse transfer capacitance	C_{rss}	—	10	—	pF	$f = 1\text{MHz}$
Turn-on delay time	$t_{d(on)}$	—	15	—	ns	$I_D = 0.1\text{A}, V_{DD} = 15\text{V}$
Rise time	t_r	—	20	—	ns	$V_{GS} = 10\text{V}$
Turn-off delay time	$t_{d(off)}$	—	90	—	ns	$R_L = 150\Omega$
Fall time	t_f	—	100	—	ns	$R_G = 10\Omega$

* $P_w \leq 300\text{ }\mu\text{s}$, Duty cycle $\leq 1\%$

● Packaging specifications

Type	Package	Taping
	Code	T146
	Basic ordering unit (pieces)	3000
2SK2731	○	

● Electrical characteristic curves

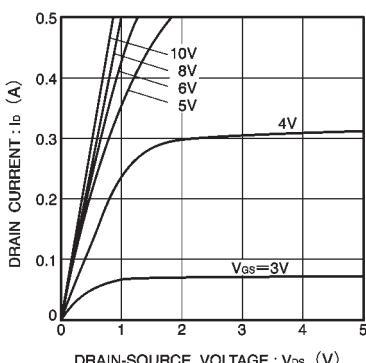


Fig.1 Typical output characteristics

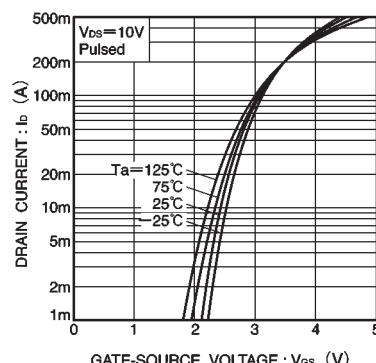


Fig.2 Typical transfer characteristics

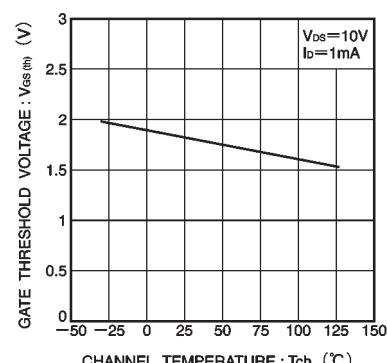


Fig.3 Gate threshold voltage vs. channel temperature

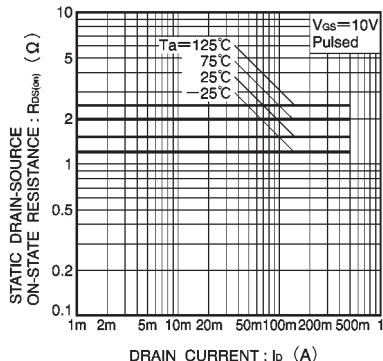


Fig.4 Static drain-source on-state resistance vs. drain current (I)

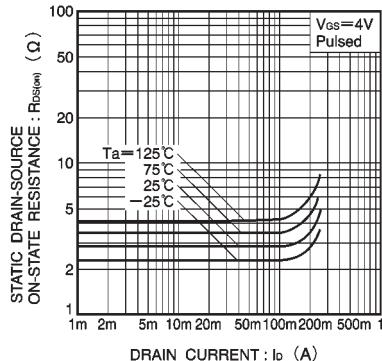


Fig.5 Static drain-source on-state resistance vs. drain current (II)

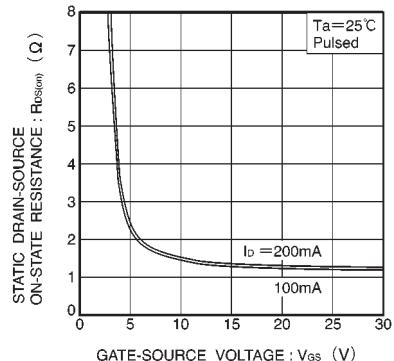


Fig.6 Static drain-source on-state resistance vs. gate-source voltage

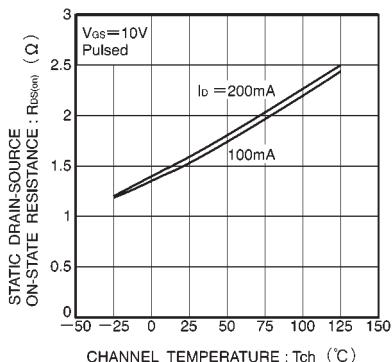


Fig.7 Static drain-source on-state resistance vs. channel temperature

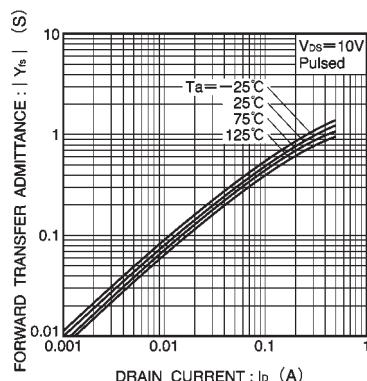


Fig.8 Forward transfer admittance vs. drain current

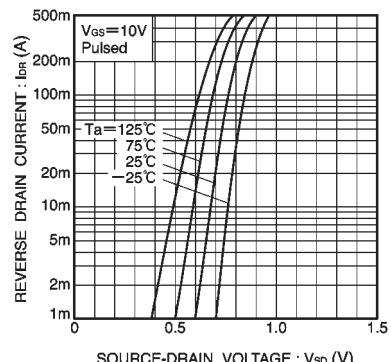


Fig.9 Reverse drain current vs. source-drain voltage (I)

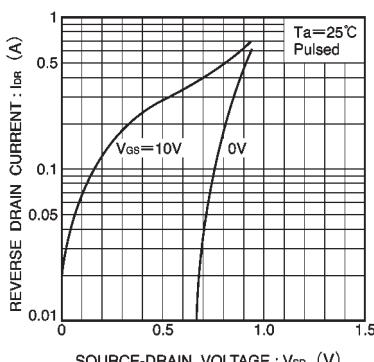


Fig.10 Reverse drain current vs. source-drain voltage (II)

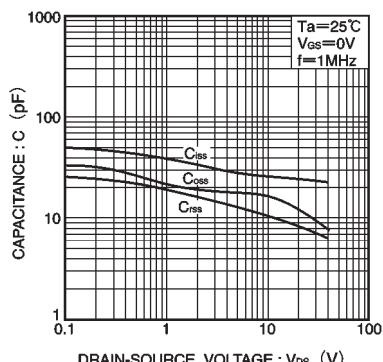


Fig.11 Typical capacitance vs. drain-source voltage

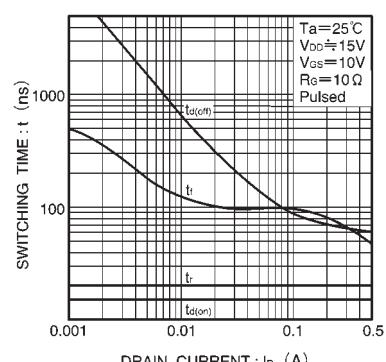


Fig.12 Switching characteristics (See Figures 13 and 14 for the measurement circuit and resultant waveforms)

- Switching characteristics measurement circuit

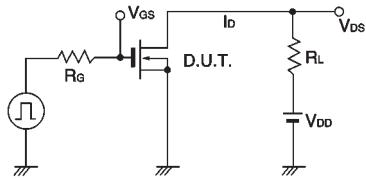


Fig.13 Switching time measurement circuit

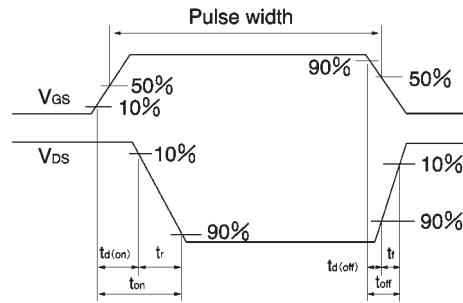


Fig.14 Switching time waveforms